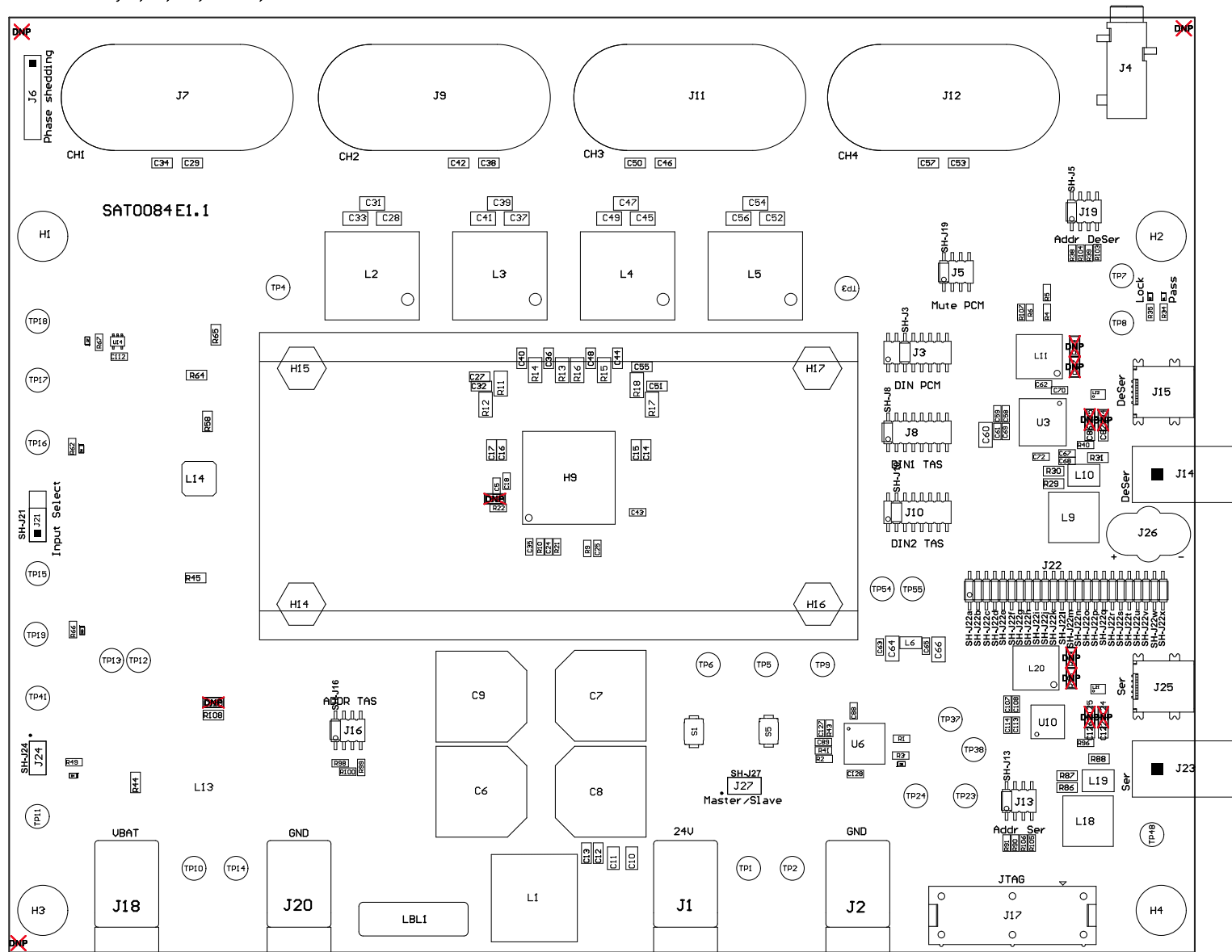
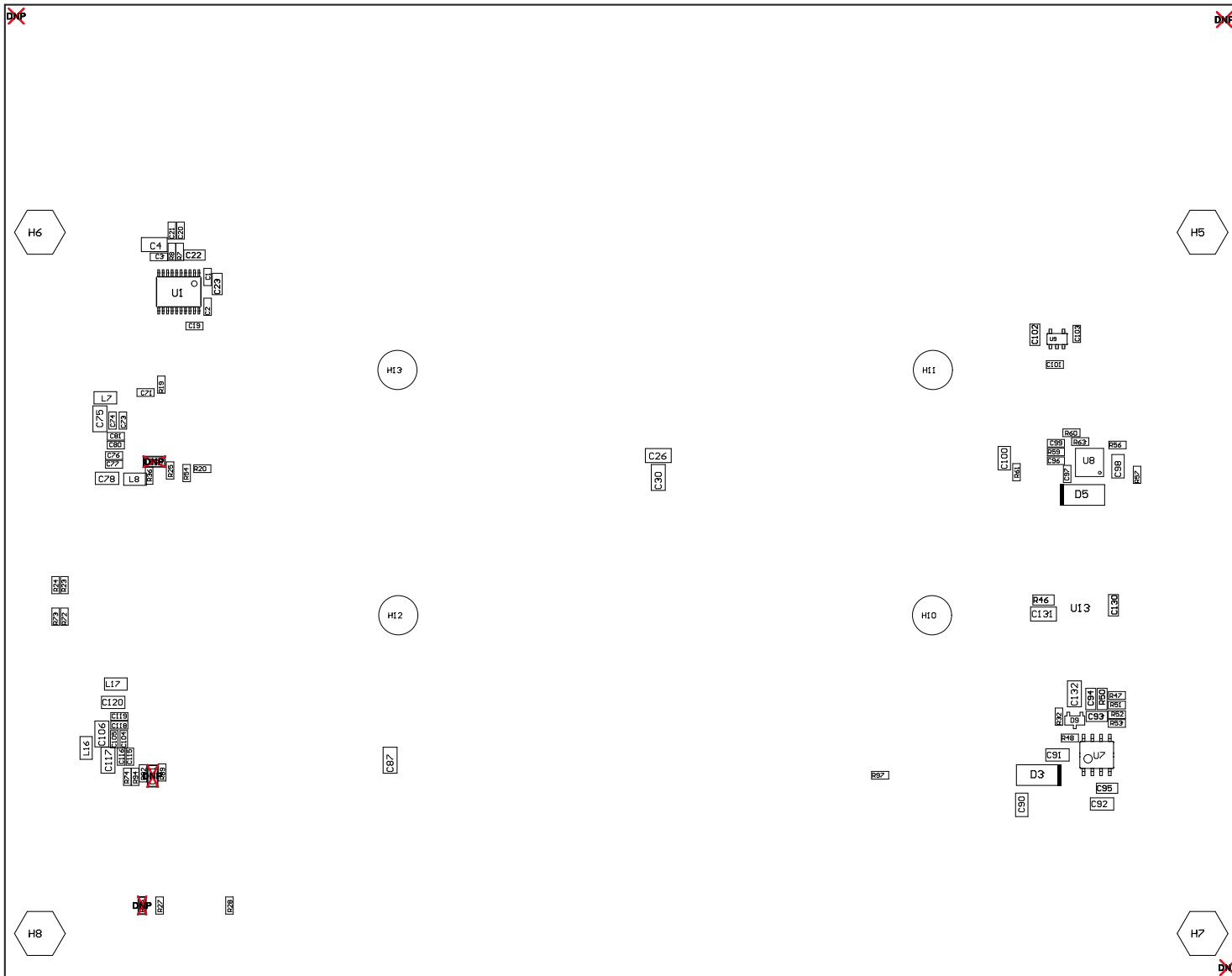


- ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ5 ■ Apply a thin layer of heatsink grease on top of U2 before installing heatsink
- ZZ6 ■ When installing J7, J8, J11, and J12, do not install the bottom-side insulator. Nuts must contact bottom copper pads.
- ZZ7 ■ When installing J1, J2, J18, and J20, solder AND bolt them



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: COAX

PCB VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 7/10/2014	11:09:35 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: COAX

PCB VIEWED FROM BOTTOM SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
	IGNORE -> μεlɹev0 ɹottoB		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/10/2014	11:09:36 AM	TEXAS INSTRUMENTS

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